

### General Description

The MDP7N50 uses advanced Magnachip's MOSFET Technology, which provides low on-state resistance, high switching performance and excellent quality.

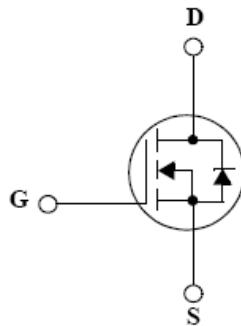
MDP7N50 is suitable device for SMPS, HID and general purpose applications.

### Features

- $V_{DS} = 500V$
- $I_D = 7.0A$  @  $V_{GS} = 10V$
- $R_{DS(ON)} < 0.9\Omega$  @  $V_{GS} = 10V$

### Applications

- Power Supply
- HID
- Lighting



### Absolute Maximum Ratings ( $T_a = 25^\circ C$ )

Characteristics	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	500	V
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Continuous Drain Current	$I_D$	7.0	A
		4.2	A
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	28	A
Power Dissipation	$P_D$	114	W
		0.91	W/ $^{\circ}C$
Peak Diode Recovery $dv/dt$ <sup>(3)</sup>	$Dv/dt$	4.5	V/ns
Single Pulse Avalanche Energy <sup>(4)</sup>	$E_{AS}$	270	mJ
Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~150	$^{\circ}C$

### Thermal Characteristics

Characteristics	Symbol	Rating	Unit
Thermal Resistance, Junction-to-Ambient <sup>(1)</sup>	$R_{\theta JA}$	62.5	$^{\circ}C/W$
Thermal Resistance, Junction-to-Case <sup>(1)</sup>	$R_{\theta JC}$	1.1	

**Ordering Information**

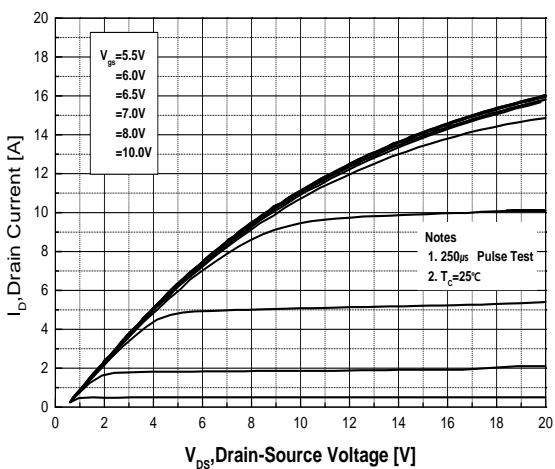
Part Number	Marking	Temp. Range	Package	Packing
MDP7N50	MDP7N50	-55~150°C	TO-220	Tube

**Electrical Characteristics (Ta =25°C)**

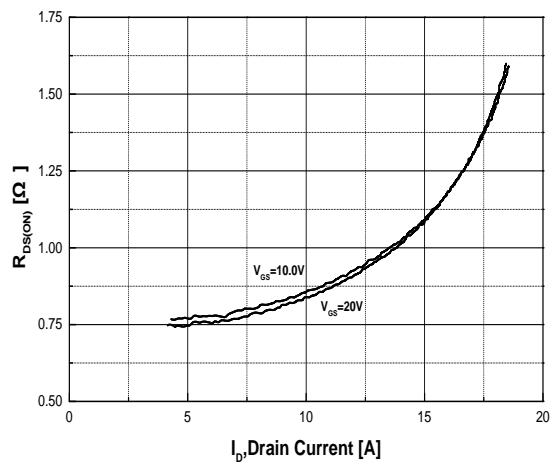
Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	BVDSS	ID = 250µA, VGS = 0V	500	-	-	V
Gate Threshold Voltage	VGS(th)	VDS = VGS, ID = 250µA	3.0	-	5.0	
Drain Cut-Off Current	IDS	VDS = 500V, VGS = 0V	-	-	1	µA
Gate Leakage Current	IGSS	VGS = ±30V, VDS = 0V	-	-	100	nA
Drain-Source ON Resistance	RDS(ON)	VGS = 10V, ID = 3.5A		0.76	0.9	Ω
Forward Transconductance	gfs	VDS = 30V, ID = 3.5A	-	7	-	S
<b>Dynamic Characteristics</b>						
Total Gate Charge	Qg	VDS = 400V, ID = 7.0A, VGS = 10V <sup>(3)</sup>	-	17.5		nC
Gate-Source Charge	Qgs		-	5		
Gate-Drain Charge	Qgd		-	6.5		
Input Capacitance	Ciss	VDS = 25V, VGS = 0V, f = 1.0MHz	-	740		pF
Reverse Transfer Capacitance	Crss		-	3.7		
Output Capacitance	Coss		-	95.5		
Turn-On Delay Time	td(on)	VGS = 10V, VDS = 250V, ID = 7.0A, RG = 25Ω <sup>(3)</sup>	-	16.8		ns
Rise Time	tr		-	29.8		
Turn-Off Delay Time	td(off)		-	36.4		
Fall Time	tf		-	23.6		
<b>Drain-Source Body Diode Characteristics</b>						
Maximum Continuous Drain to Source Diode Forward Current	Is	Is = 7.0A, VGS = 0V	-	7.0	-	A
Source-Drain Diode Forward Voltage	VSD		-		1.4	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 7.0A, dI/dt = 100A/µs <sup>(3)</sup>	-	260		ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>		-	1.7		µC

Note :

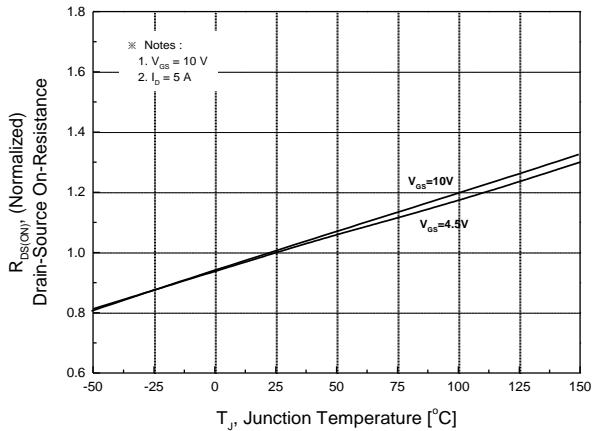
1. Pulse width is based on RθJC & RθJA and the maximum allowed junction temperature of 150°C.
2. Pulse test: pulse width ≤300us, duty cycle≤2%, pulse width limited by junction temperature TJ(MAX)=150°C.
3. I<sub>SD</sub> ≤ 7.0A, di/dt≤200A/us, VDD=50V, R<sub>G</sub> =25Ω, Starting TJ=25°C
4. L=10mH, I<sub>AS</sub>=7.0A, V<sub>DD</sub>=50V, , R<sub>G</sub> =25Ω, Starting TJ=25°C



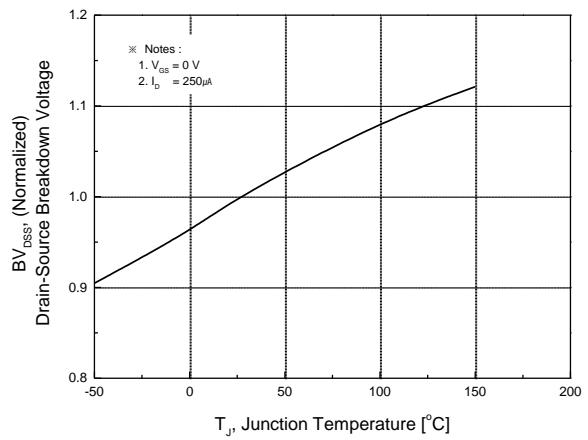
**Fig.1 On-Region Characteristics**



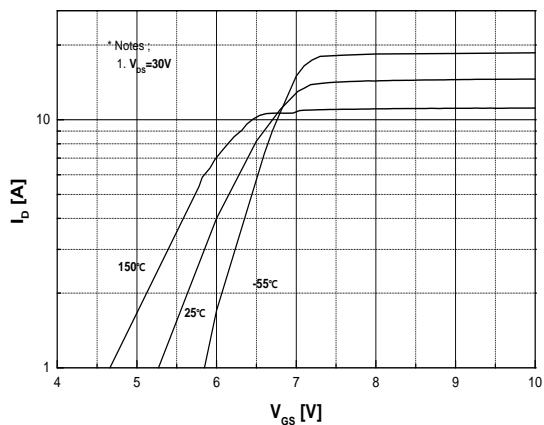
**Fig.2 On-Resistance Variation with Drain Current and Gate Voltage**



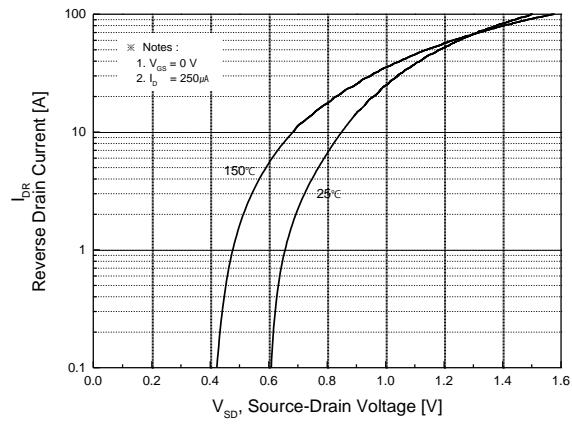
**Fig.3 On-Resistance Variation with Temperature**



**Fig.4 Breakdown Voltage Variation vs. Temperature**



**Fig.5 Transfer Characteristics**



**Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature**

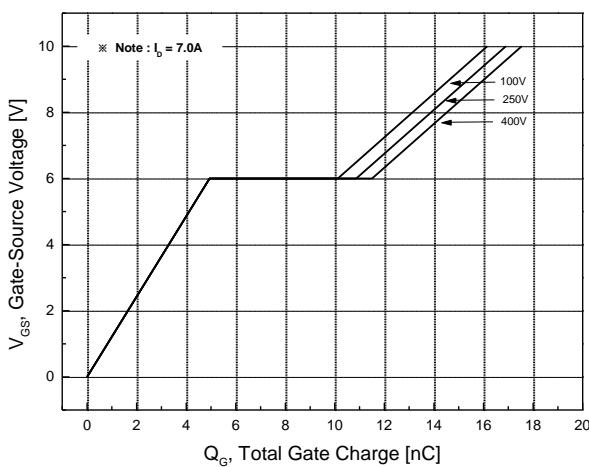


Fig.7 Gate Charge Characteristics

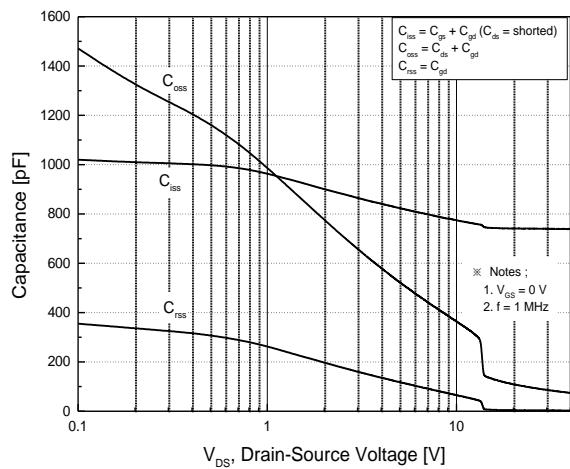


Fig.8 Capacitance Characteristics

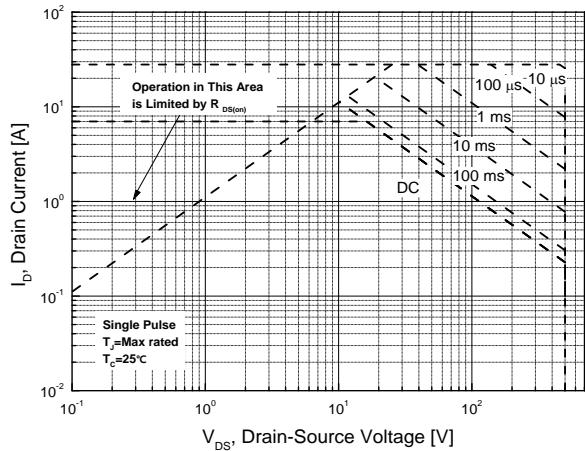


Fig.9 Maximum Safe Operating Area

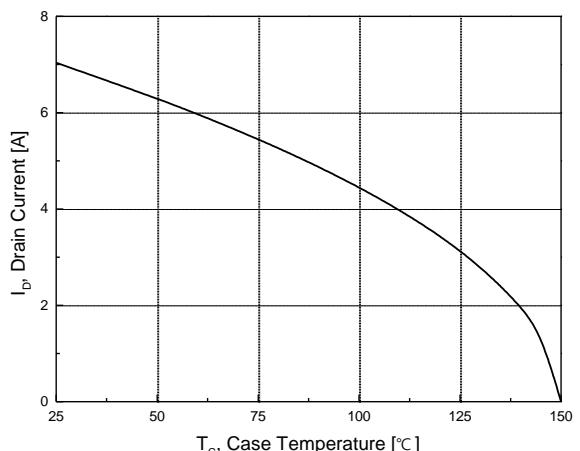


Fig.10 Maximum Drain Current vs. Case Temperature

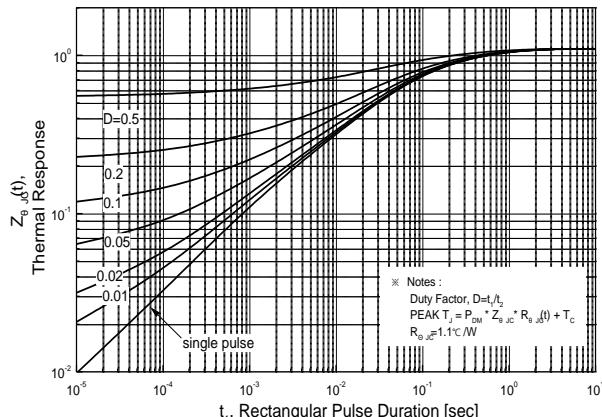


Fig.11 Transient Thermal Response Curve

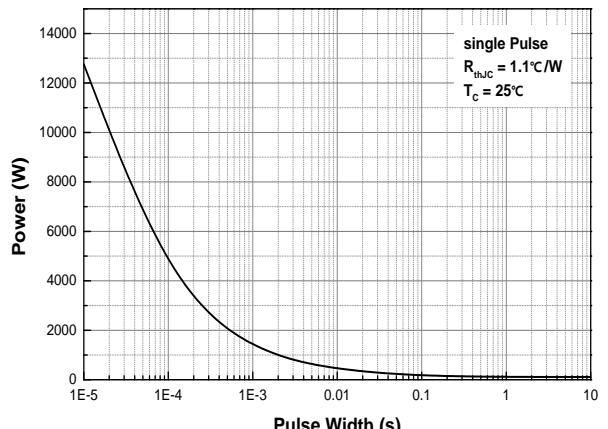
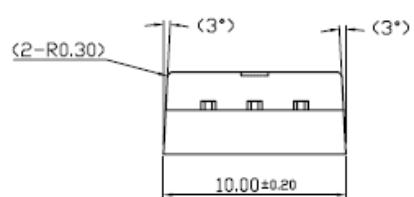
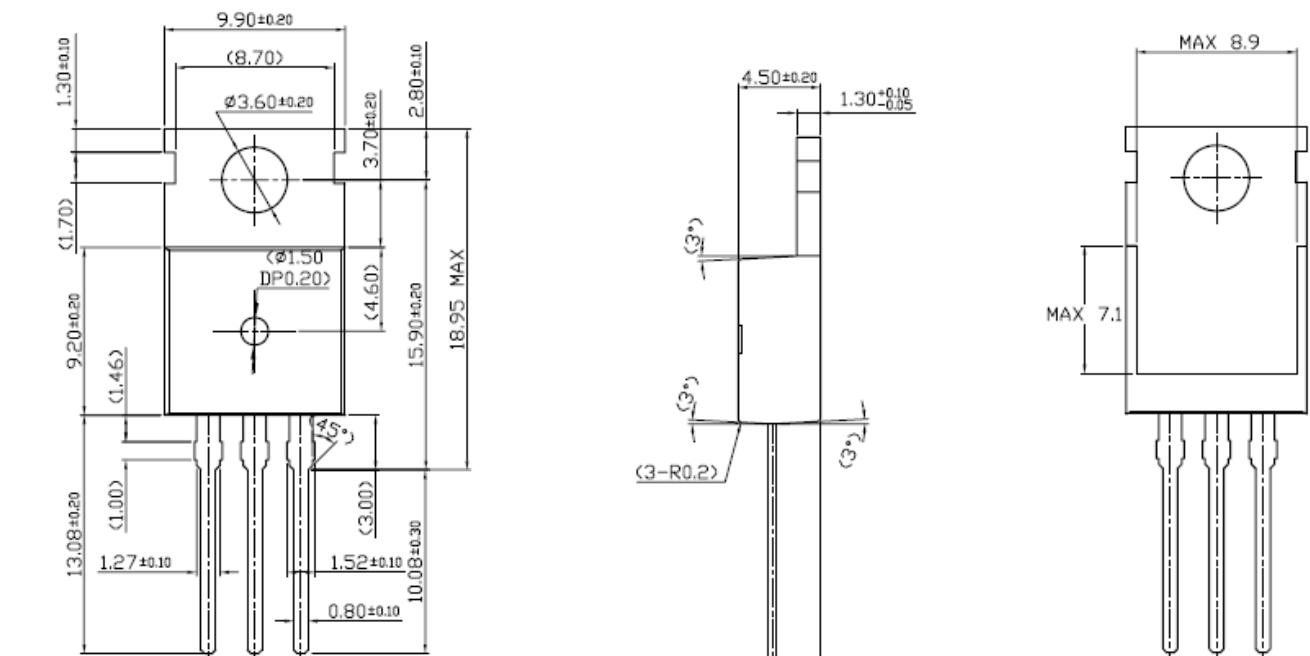


Fig.12 Single Pulse Maximum Power Dissipation

## Physical Dimension

### TO-220

Dimensions are in millimeters, unless otherwise specified



**DISCLAIMER:**

The Products are not designed for use in hostile environments, including, without limitation, aircraft, nuclear power generation, medical appliances, and devices or systems in which malfunction of any Product can reasonably be expected to result in a personal injury. Seller's customers using or selling Seller's products for use in such applications do so at their own risk and agree to fully defend and indemnify Seller.

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